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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

pplicant: Premakaran T. Boaz and John Pereira

Application No.:

10/802,387

Group: 1742

Filed:

March 17, 2004

Examiner: Not Assigned

Confirmation No.:

3670

For:

SOLDER COMPOSITION

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INFORMATION DISCLOSURE STATEMENT

Mail Stop Amendment Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Sir:

	under 37 CFR 1.129(a), or (First/Second submission after Final Rejection)
[X]	under 37 CFR 1.97(b), or (Within any one of the following time periods: three months of fili

(Within any one of the following time periods: three months of filing national application (other than a CPA) or date of entry of the national stage in an international application; or before the mailing date of a first office action on the merits in a non-provisional application, including a CPA, or a Request for Continued Examination).

[] a \$180.00 fee under 37 CFR 1.17(p), or (After the 37 CFR 1.97(b) time period, but before final action or notice of allowance, whicheve under 37 CFR 1.97(d) together with: [] a Statement under 37 CFR 1.97(e), as checked below, and [] a \$180.00 fee under 37 CFR 1.17(p), or		CPA, of a Request for Commueu Examination).
[] a \$180.00 fee under 37 CFR 1.17(p), or (After the 37 CFR 1.97(b) time period, but before final action or notice of allowance, whicheve under 37 CFR 1.97(d) together with: [] a Statement under 37 CFR 1.97(e), as checked below, and [] a \$180.00 fee under 37 CFR 1.17(p), or	[]	under 37 CFR 1.97(c) together with either:
(After the 37 CFR 1.97(b) time period, but before final action or notice of allowance, whicheve under 37 CFR 1.97(d) together with: [] a Statement under 37 CFR 1.97(e), as checked below, and [] a \$180.00 fee under 37 CFR 1.17(p), or		[] a Statement under 37 CFR 1.97(e), as checked below, or
[] a Statement under 37 CFR 1.97(e), as checked below, an [] a \$180.00 fee under 37 CFR 1.17(p), or		[] a \$180.00 fee under 37 CFR 1.17(p), or (After the 37 CFR 1.97(b) time period, but before final action or notice of allowance, whichever occurs first)
[] a \$180.00 fee under 37 CFR 1.17(p), or	[]	under 37 CFR 1.97(d) together with:
477		[] a Statement under 37 CFR 1.97(e), as checked below, and
		[] a \$180.00 fee under 37 CFR 1.17(p), or (Filed after final action or notice of allowance, whichever occurs first, but on or before payment of the issue fee)

[] under 37 CFR 1.97(i):

Applicant requests that the IDS and cited reference(s) be placed in the application filewrapper. (Filed after payment of issue fee)

Statem	ient Un	<u>der 3/C</u>	CFR 1.97(e)	
	Each item of information contained in this Information Disclosure Statement was first cited in any communication from a foreign patent office in a counterpart foreign application not more than three months prior to the filing of this Information Disclosure Statement; or			
[]	No item of information contained in this Information Disclosure Statement was cited in a communication from a foreign patent office in a counterpart foreign application, and, to the knowledge of the undersigned, after making reasonable inquiry, no item of information contained in the information disclosure statement was known to any individual designated in 37 CFR 1.56(c) more than three months prior to the filing of this Information Disclosure Statement.			
Statem	ent Un	der 37 ((Patent Term Adjustment) Applies to original applications (other than design) filed on or after May 29, 2000	
[]	comm was no	unication ot receiv	nformation contained in the Information Disclosure Statement was cited in a n from a foreign patent office in a counterpart application and this communication red by any individual designated in § 1.56(c) more than thirty days prior to the formation Disclosure Statement.	
[X]	Enclos	sed here	with is form PTO-1449:	
	[X] Copies of the cited references are enclosed.			
		[X]	Since this application was filed after June 30, 2003, copies of issued U.S. patents and published U.S. applications are not required and are not being provided.	
	[]	Applic	of the cited references are enclosed except those entered in prior application, U.S. ation No. [], to which priority under 35 U.S.C. 120 is claimed. [The earlier ation contains copies of the cited references.]	
	[]	The list	sted references were cited in the enclosed International Search Report in a rpart foreign application.	
	[]		oncise explanation" requirement (non-English references) for reference(s) [37 CFR 1.98(a)(3) is satisfied by:	
		[]	the explanation provided on the attached sheet.	
		[]	the explanation provided in the Specification.	
		[]	submission of the enclosed International Search Report.	
		[]	submission of the enclosed English-language version of a foreign Search Report and/or foreign Office Action.	
		[]	the enclosed English language abstract.	

[]	Applic	cant requests that the following n	non-published pending applic	cations be considered:
Examiner's Initials				
		U.S. Patent Application No. [], by [inventor(s)], filed [], Docket No.: []
		U.S. Patent Application No. [], by [inventor(s)], filed [], Docket No.: []
		U.S. Patent Application No. [], by [inventor(s)], filed [], Docket No.: []
		Examiner	Date	_
	[]	A copy of each above-cited app	olication, including the curre	nt claims, is enclosed.
	[]	A copy of each above-cited app those entered in prior application 35 U.S.C. 120 is claimed.	olication, including the curre on, U.S. Application No. [nt claims, is enclosed, except], to which priority under
The Ex	xamine nces we	r is requested to return a copy of re considered with the next offic	the above list of pending ap e communication.	plications indicating which
It is re	quested	that the information disclosed h	erein be made of record in the	nis application.
Metho	d of pa	yment:		
[]		ck for the fee noted above is encloped above is encloped above is enclosed. A copy of this S		cluded in the check with the
[]	Please	charge Deposit Account 08-038 ed.	0 in the amount of \$[. A copy of this Statement is
[X]	Please charge any deficiency in fees and credit any overpayment to Deposit Account 08-0380.			
		F	Respectfully submitted,	•
			Darrell L. Wong Registration No.: 36,725 Telephone: (978) 341-0036 Facsimile: (978) 341-0136)

Concord, MA 01742-9133 Dated: 7/72/2004

PTO-1449 REPRODUCED	ATTORNEY DOCKET NO. 2678.2011-000	APPLICATION NO. 10/802,387		
P ENFORMATION DISCLOSURE CITATION IN AN APPLICATION	FIRST NAMED INVENTOR Premakaran T. Boaz		FILING DATE March 17, 2004	
July 20, 2004 July 20, 2004 System Several sheets if necessary)	EXAMINER not assigned		IRMATION NO.	GROUP not assigned

PER	TRADEM			
	TRAU	U.S	6. PATENT DOCUMENTS	
EXAM- INER INI- TIAL	REF. NO.	DOCUMENT NUMBER Number-Kind Code (if known)	ISSUE DATE / PUBLICATION DATE MM-DD-YYYY	NAME OF PATENTEE OR APPLICANT OF CITED DOCUMENT
	AA	5,066,544	11/19/1991	Betrabet et al.
	AB	5,384,090	01/24/1995	Ogashiwa
	AC	5,918,795	07/06/1999	Yamaguchi et al.
	AD	US 6,253,988 B1	07/03/2001	Pereira
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PTO-1449 REPRODUCED	ATTORNEY DOCKET NO. APPLICATION 2678.2011-000 10/802,38		PLICATION NO. /802,387	
INFORMATION DISCLOSURE CITATION IN AN APPLICATION	FIRST NAMED INVENTOR Premakaran T. Boaz		FILING DATE March 17, 2004	
July 20, 2004	EXAMINER	CONF	IRMATION NO.	GROUP
(Use several sheets if necessary)	not assigned	not a	assigned	not assigned

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)				
	AR	Lee, NC., "Getting Ready for Lead-free Solders," Soldering & Surface Mount Technology, 26: 64-69 (July 1997).		
	AS	Hwang, J.S., "Lead-free Solders," <i>Modern Solder Technology for Competitive Electronics Manufacturing</i> , Chapter 15: pp. 483-509, McGraw-Hill (1996).		
	AT	Beal, RE. and Bader, W.G., "Soldering," Chapter in book, Edited by O'Brien, R.L., Welding Handbook, vol. 2, Chapter 13: pp. 423-447 (1991).		
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